Preface

This volume contains some selected papers from the 2017 Electronic Packaging Interconnect Technology Symposium (EPITS 2017) which is held in Fukuoka, Japan during November 1 - 2, 2017. This conference is jointly organized by The University of Queensland (UQ), Universiti Malaysia Perlis (UniMAP), Kyusyu University and Malaysia Japan International Institute of Technology (MJIIT). The conference aims to provide a high level international forum in order to bring together researchers, technologist, and professionals for Academic, Industrial and Public Sector to present their new advances and research results in the field of Electronic Packaging Interconnect Technology.

This volume covers many aspects of topics of interest such as challenges in implementing the Restriction of Hazardous Substances (ROHS), emerging interconnect materials and technologies, solders for interconnection at chip and package levels, stress-migration and mechanical properties of the solder connections, advanced characterization methods as applied to electronic packaging technology, whisker growth in tin, tin-based alloys and other metallic systems related to soldering in the electronics and also developments in high temperature Pb-free solders and associated interconnects for automotive and power electronics. All of the papers have been reviewed by more than two expert referees in their relevant topic disciplines. The paper selected for this volume depended on their quality and relevancy to the conference.

The editors hope that this volume will provide the reader a broad overview of the latest advances in the field of Electronic Packaging Interconnect Technology, and that will be as valuable reference source for further research.

The editors would like to express their sincere appreciations and thanks to all the committee members of the EPITS 2017 for their tremendous efforts. Without their dedication it was impossible to have a successful EPITS 2017 and a high quality volume of the conference proceedings. Finally, the editors would like to thanks all the authors for their contribution to this valuable volume.

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Universiti Malaysia Perlis, MALAYSIA

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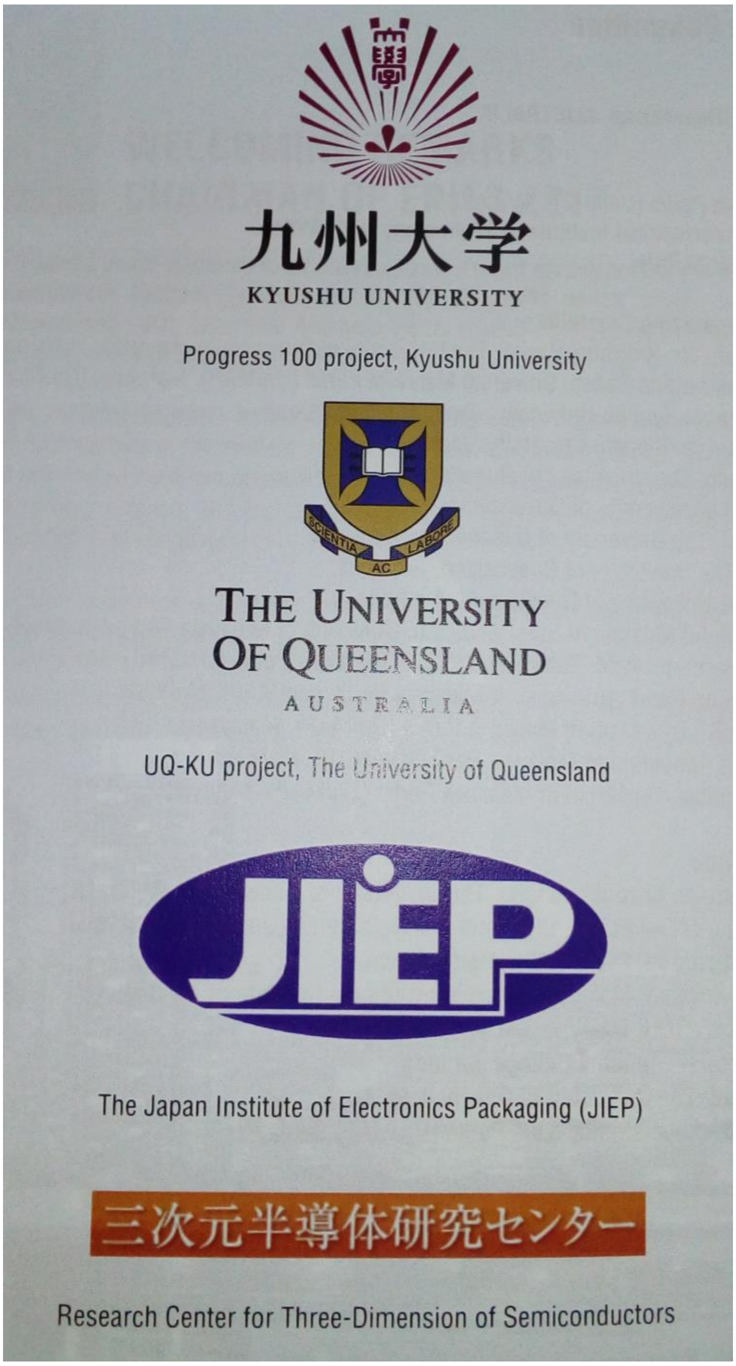

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